Product Change Notification

106465 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 106465 - 00

Change Title: Intel® RC2700G5 Multimedia Accelerator, PCN 106465-00, Product Discontinuance

Date of Publication: June 30, 2006

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Product Discontinuance Program Support Begins:	Jun 30, 2006
Product Discontinuance Demand To Local Intel Representative:	Mar 30, 2007
Last Product Discontinuance Order Date(non-cancelable):	Jun 30, 2007
Last Product Discontinuance Shipment Date:	Dec 30, 2007

Description of Change to the Customer:

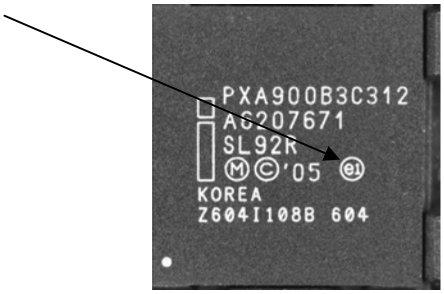
In support of the worldwide initiative to remove non Pb-Free components from electronic equipment and in response to decreasing customer demand, the non Pb-Free versions of the Intel® 2700G5 Multimedia Accelerator will be discontinued and unavailable for additional orders after the "Last Product Discontinuance Order Date" (see "Forecasted Key Milestones" above).

Please refer to the "Products Affected / Intel Ordering Codes" table below for the 2700G5 Multimedia Accelerator included in this notification.

The products listed in the table below have undergone the following changes, in order to be compliant with Intel’s Pb-Free/RoHS Initiative:

1. SLI (Second Level Interconnect) solder ball material has been changed from Sn/Pb (tin/lead) to Sn/Ag/Cu (tin/silver/copper) alloy.
2. Pb-Free products are Pb-Free board process compatible and their peak reflow temperature has been increased to 260°C (non Pb-Free peak reflow temperature is 240°C).
3. A new marking “e1” with a circle around it has been added to the top-side product mark per Intel Marking/Labeling Specification #CG-1034 indicating the product SLI is now Pb-Free (see example below).

Pb-Free “e1” Mark
(Example Only)



Note: Non Pb-Free material has not been intentionally added, but may still exist as an impurity below 1000 ppm.

Finally, the Product Codes and Material Master Numbers (MM#) have been changed to reflect the new Pb-Free packaging as shown below, in the “Products Affected/Intel Ordering Codes” table.

Customer Impact of Change and Recommended Action:

Customers are requested to determine their remaining demand for the non Pb-Free 2700G5 Multimedia Accelerator affected by this PCN and place their “Last Product Discontinuance Orders" in accordance with the "Forecasted Key Milestones" listed above.

Options exist for upgrading non Pb-Free 2700G5 Multimedia Accelerator-based designs to Pb-Free 2700G5 Multimedia Accelerator-based designs, however replacement of non Pb-Free 2700G5 Multimedia Accelerator by the Pb-Free 2700G5 Multimedia Accelerator may require varying degrees of engineering design and manufacturing process consideration.

1. Pb-Free SLI products require a new Pb-Free board assembly process. Customers should develop their own board profile envelope appropriate to their equipment, material and products.
2. The new Pb-Free products are not “drop in” replacements or backward compatible with the non Pb-Free board process. Intel recommends running solder joint evaluations in case Pb-Free SLI parts are to be used in a non Pb-Free board assembly process.
3. The appearance of Sn/Ag/Cu solder balls may be grainy and dull when compared to Sn/Pb balls. This may require an adjustment to visual inspection system hardware and software.

Please contact your local Intel Sales Representative for more information.

Non Pb-Free versions of the 2700G5 Multimedia Accelerator will no longer ship after December 30, 2007.

Intel reserves the right to ship aged non Pb-Free material to fulfill partial or all Last Product Discontinuance Shipments.

Products Affected / Intel Ordering Codes:

Component Product Table

Pre-Conversion Product Code	Pre-Conversion MM#	Post-Conversion MM#	Post-Conversion Product Code
RC2700G5 SL7K5	861712	863105	RT2700G5 SL7K6

Reference Documents / Attachments:

Document:	**Location #:**
Intel Pb-Free Site	http://www.intel.com/research/silicon/leadfree.htm
MDDS (Material Declaration Datasheet)	http://www.intel.com/design/PACKTECH/packbook.htm

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
June 30, 2006	00	Originally Published PCN